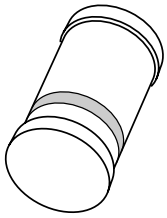
DATA SHEET



PMLL4148L; PMLL4448
High-speed diodes

Product specification
Supersedes data of 2000 Nov 15

2002 Jan 23

Philips
Semiconductors

PHILIPS

High-speed diodes PMLL4148L; PMLL4448

FEATURES

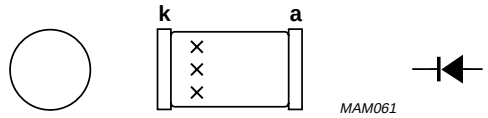
- Small hermetically sealed glass SMD package
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 100 V
- Repetitive peak forward current: max. 450 mA.

APPLICATIONS

- High-speed switching
- Fast logic applications.

DESCRIPTION

The PMLL4148L and PMLL4448 are high-speed switching diodes fabricated in planar technology, and encapsulated in small hermetically sealed glass SOD80C SMD packages. PMLL4148L was formerly named PMLL4148 and has no difference to this type in technical specification, processing, packing or labelling.



The marking band indicates the cathode.

Fig.1 Simplified outline (SOD80C) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		–	100	V
V_R	continuous reverse voltage		–	75	V
I_F	continuous forward current	see Fig.2; note 1	–	200	mA
I_{FRM}	repetitive peak forward current		–	450	mA
I_{FSM}	non-repetitive peak forward current	square wave; T_j = 25 °C prior to surge; see Fig.4			
		t = 1 μs	–	4	A
		t = 1 ms	–	1	A
		t = 1 s	–	0.5	A
P_{tot}	total power dissipation	T_{amb} = 25 °C; note 1	–	500	mW
T_{stg}	storage temperature		–65	+200	°C
T_j	junction temperature		–	200	°C

Note

1. Device mounted on an FR4 printed-circuit board.

ELECTRICAL CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_F	forward voltage	see Fig.3			
	PMLL4148L	I_F = 10 mA	–	1	V
	PMLL4448	I_F = 5 mA	620	720	mV
		I_F = 100 mA	–	1	V
I_R	reverse current	V_R = 20 V; see Fig.5		25	nA
		V_R = 20 V; T_j = 150 °C; see Fig.5	–	50	µA
I_R	reverse current; PMLL4448	V_R = 20 V; T_j = 100 °C; see Fig.5	–	3	µA
C_d	diode capacitance	f = 1 MHz; V_R = 0; see Fig.6		4	pF
t_{rr}	reverse recovery time	when switched from I_F = 10 mA to I_R = 60 mA; R_L = 100 Ω; measured at I_R = 1 mA; see Fig.7		4	ns
V_{fr}	forward recovery voltage	when switched from I_F = 50 mA; t_r = 20 ns; see Fig.8	–	2.5	V

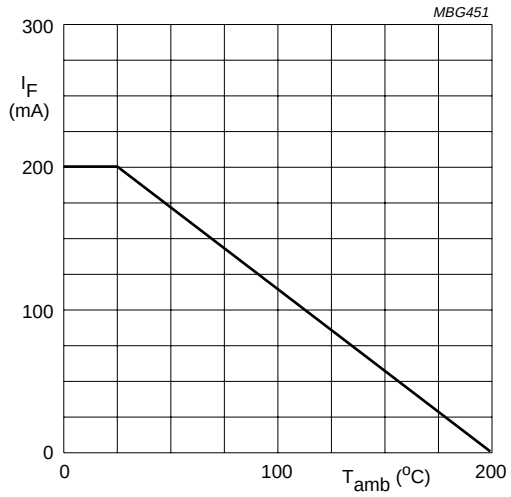
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}tp}$	thermal resistance from junction to tie-point		300	K/W
$R_{th\ j\text{-}a}$	thermal resistance from junction to ambient	note 1	350	K/W

Note

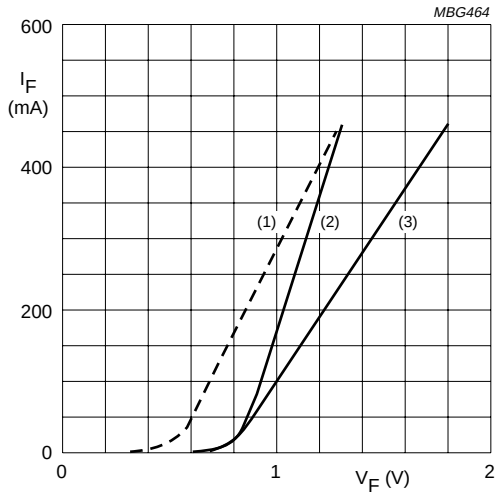
1. Device mounted on an FR4 printed-circuit board.

GRAPHICAL DATA



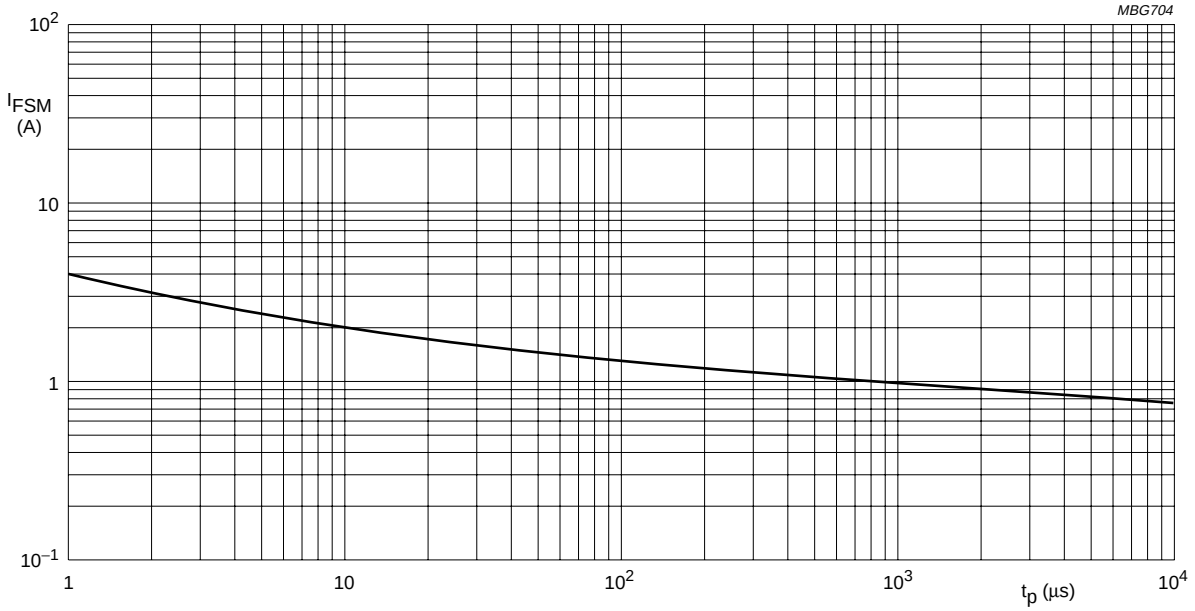
Device mounted on an FR4 printed-circuit board.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



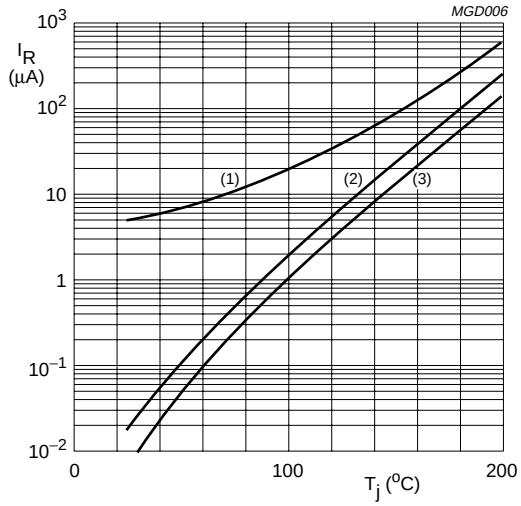
(1) T_j = 175 °C; typical values.
(2) T_j = 25 °C; typical values.
(3) T_j = 25 °C; maximum values.

Fig.3 Forward current as a function of forward voltage.



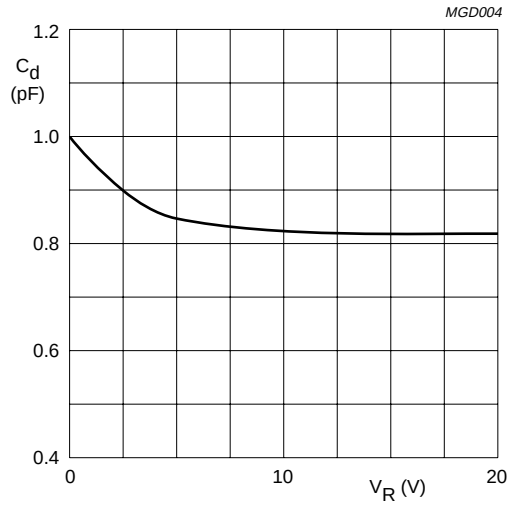
Based on square wave currents.
T_j = 25 °C prior to surge.

Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.



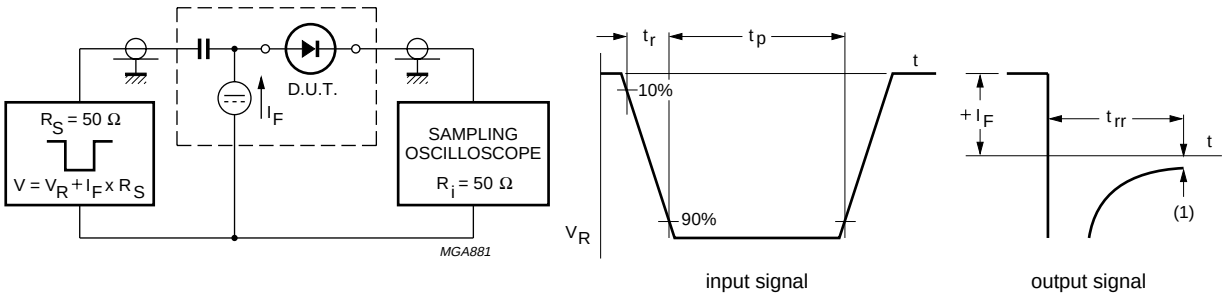
(1) V_R = 75 V; maximum values.
(2) V_R = 75 V; typical values.
(3) V_R = 20 V; typical values.

Fig.5 Reverse current as a function of junction temperature.



f = 1 MHz; T_j = 25 °C.

Fig.6 Diode capacitance as a function of reverse voltage; typical values.



(1) I_R = 1 mA.

Fig.7 Reverse recovery voltage test circuit and waveforms.

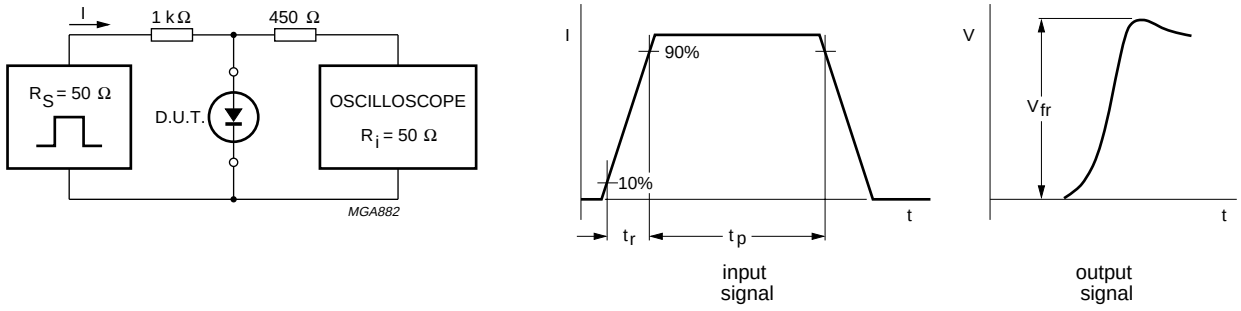
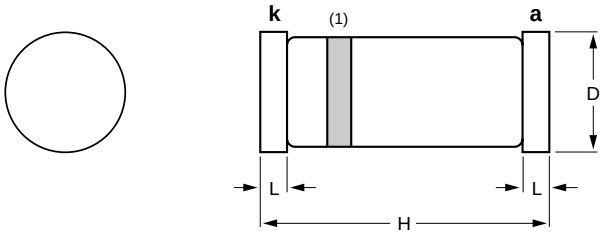


Fig.8 Forward recovery voltage test circuit and waveforms.

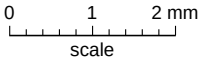
PACKAGE OUTLINE

Hermetically sealed glass surface mounted package; 2 connectors **SOD80C**



DIMENSIONS (mm are the original dimensions)

UNIT	D	H	L
mm	1.60 1.45	3.7 3.3	0.3



Note

1. The marking band indicates the cathode.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOD80C	100H01					97-06-20

DATA SHEET STATUS

DATA SHEET STATUS[1]	PRODUCT STATUS[2]	DEFINITIONS
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